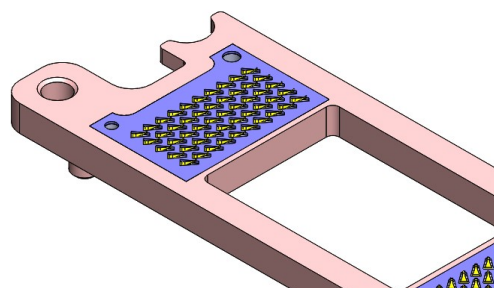


100-Position LGA/LGA PCBeam™ Connector

Neoconix P/N: BDX0100CMMHFAU00

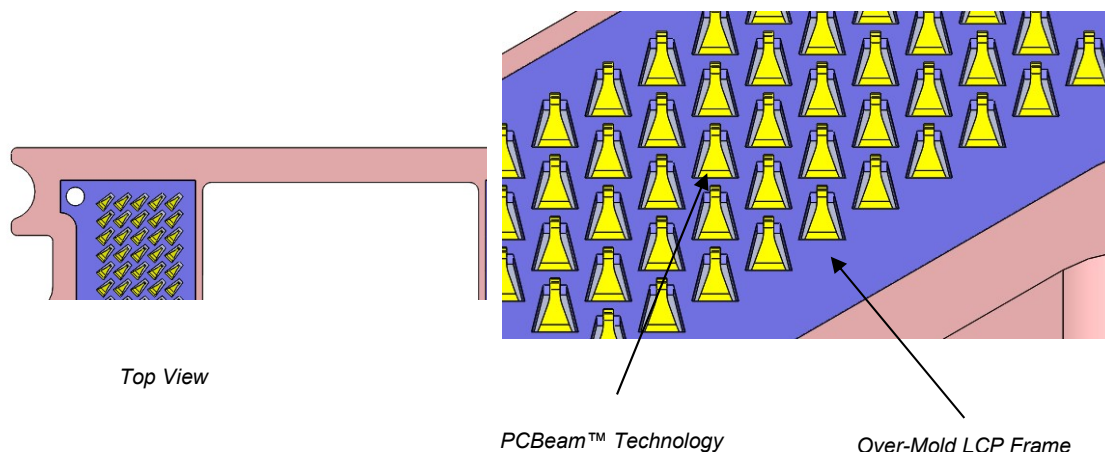
FEATURES

- High density 0.7424mm area-array pitch
- Low profile, 1.60 mm mated height
- PCBeam™ high reliability LGA spring contacts
- Over-molded plastic frame for improved dimensional tolerances
- Hard gold-plated contact interface
- RoHS 2011/65/EU (RoHS2) compliant



OVERVIEW

The PCBeam™ 100 Position Connector is an interconnect solution for the Texas Instruments DLP4710 (S312 DMD). This one-piece, high density and cost effective solution is enabled by the use of an over-molded plastic frame which integrates two 50 position PCBeam™ interposers, a heat-sink opening, and features for precise alignment of the Interposers to the DMD and main PC Board.



DOCUMENT NUMBER: AS-000024	REV. E 3/5/2021	100-pin Interposer	AUTHOR: WT	Page 1 of 6
--------------------------------------	---------------------------	--------------------	----------------------	-----------------------

CROSS REFERENCE INFO:

- TI Interposer Drawing: 2513791
- TI DMD Drawing: 2513652

ORDERING INFORMATION:

- Part Number: BDx0100CMMHFAU00
- Production Packaging: Vacuum formed Low Profile Matrix Trays
- Minimum Production Order Quantity: 3,000
- Lead Times: 8 weeks ARO

SPECIFICATIONS
MECHANICAL

Contact Configuration.....	single-beam
Contact Pitch.....	0.7424mm x 0.7424mm
Contact Count.....	100 (10x5x2)
Target Load / Contact.....	30 ± 10 grams
Contact Deflection.....	0.18 mm typical per side

ELECTRICAL

Current Rating.....	0.5A per position
Resistance.....	< 50mΩ per position
Dielectric Withstanding Voltage.....	100VDC

ENVIRONMENTAL

Operating Temperature.....	-20°C to 85°C
Storage Temperature.....	-40°C to 85°C
Heat aging.....	85°C, 96hrs,
High temperature Humidity.....	96 hrs, 90% RH, 60°C
Low temperature/ Ambient Humidity	96 hrs, -25 °C
Temperature Cycling	32 cycles, -25°C to 60°C
Thermal Shock.....	32 cycles, -25°C to 60°C
Salt Spray.....	48hrs, 5% mist
Random Vibration.....	10-55Hz rms, 3 axes, 2hrs/axis
Insertions.....	50 mating cycles

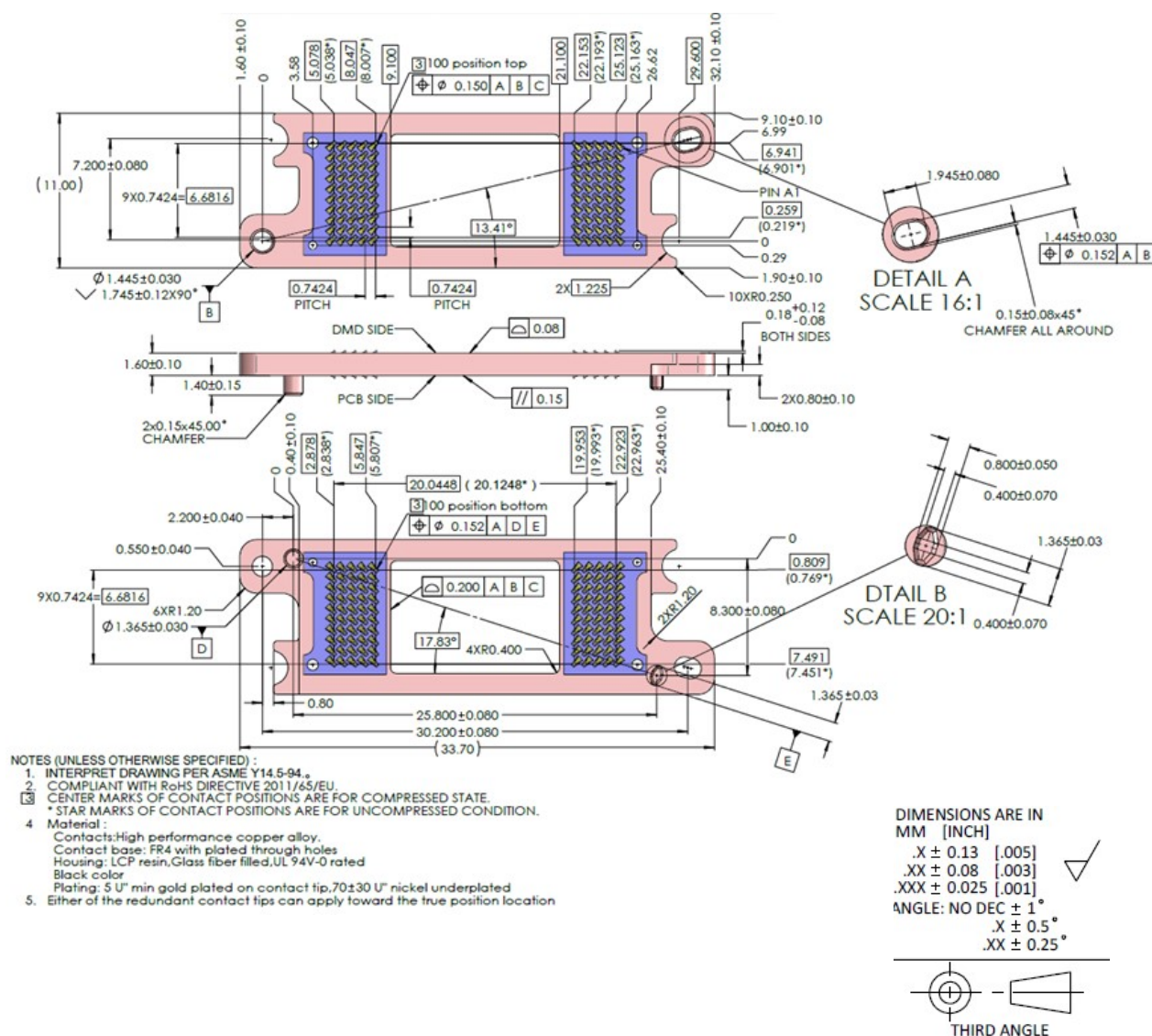
MATERIALS

Core Dielectric.....	FR4
Frame.....	LCP, UL 94V-0
Contact Elements.....	Copper alloy
Contact Plating.....	hard Au over Ni
Surface Insulator.....	polyimide or soldermask

NOTE: Specifications are subject to change without notice.

DOCUMENT NUMBER: AS-000024	REV. E 3/5/2021	100-pin Interposer	AUTHOR: WT	Page 2 of 6
--------------------------------------	---------------------------	--------------------	----------------------	-----------------------

DIMENSIONAL INFORMATION



NOTES: UNLESS OTHERWISE SPECIFIED:

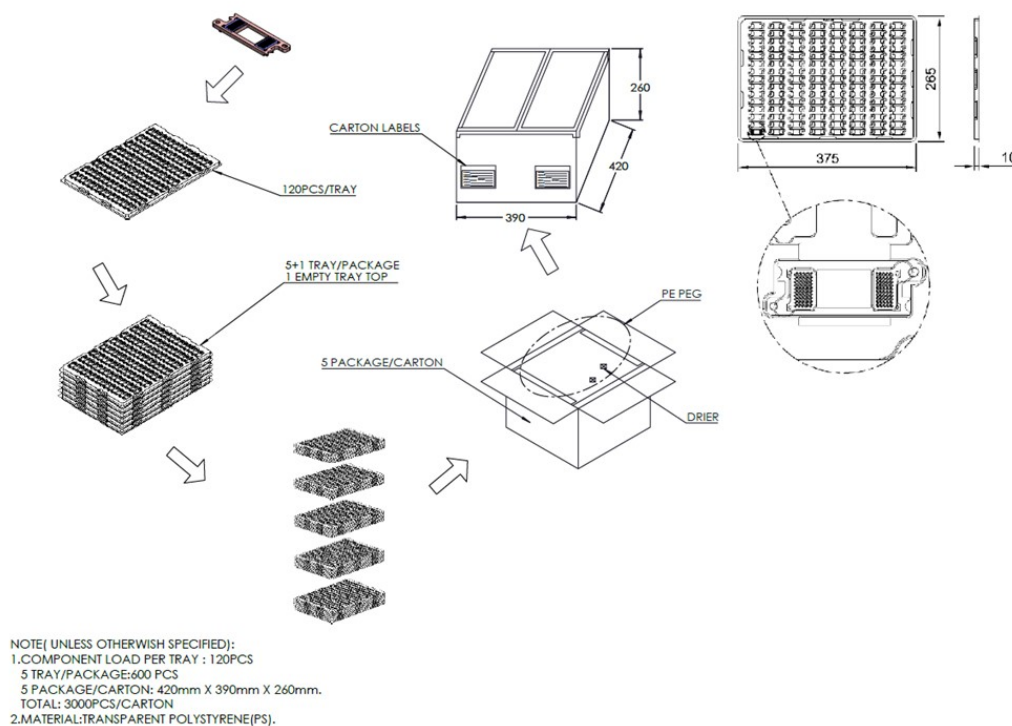
- 1 PADS TO BE ELECTROLESS NICKEL / IMMERSION GOLD (ENIG) PLATED
- 2 VIAS IN PAD AREAS MUST BE FILLED
- 3 INTERPOSER OUTLINE; NO COMPONENTS ALLOWED WITHIN THIS AREA
- 4 ALLOWED COMPONENT AREA; MAXIMUM COMPONENT HEIGHT 1.3 mm
- 5 IF SOLDERMASK IS APPLIED IN THE ARRAY AREA, IT SHALL NOT PROTRUDE ABOVE THE PLANE OF THE CONTACT PAD SURFACE

DOCUMENT NUMBER: AS-000024	REV. E 3/5/2021	100-pin Interposer	AUTHOR: WT	Page 4 of 6
--------------------------------------	---------------------------	--------------------	----------------------	-----------------------

- The use of latex gloves is recommended when handling interposers. As with any normal force connector, avoid touching contact tips and handle the product only by its edges.
- When clamping the module, PCB, or FPC onto the connector, please ensure that the force is applied uniformly. Force should be applied vertically through the z-axis and not in an angled direction.
- Cleaning is typically not needed if the product is kept in original packaging. When necessary, cleaning can be employed with the use of compressed air. Direct the flow of air in the direction that the contact elements are pointing. Cleaning can also be performed with an ultrasonic bath of isopropyl alcohol (IPA). A 5 minute soak can be followed by a 10 minute bake at 65°C.
- When not in use, please keep product stored in original packaging.

PACKAGING INFO

Production parts are provided in low profile vacuum formed trays. Each tray holds 120 pcs.



ORDERING INFO

DOCUMENT NUMBER: AS-000024	REV. E 3/5/2021	100-pin Interposer	AUTHOR: WT	Page 5 of 6
--------------------------------------	---------------------------	--------------------	----------------------	-----------------------



For order related information, please contact the Neoconix sales office at sales@neoconix.com or 408-530-9393.

Corporate Headquarters:

Neoconix, Inc.
4020 Moorkpark Avenue, #108
San Jose, CA 95117 USA
<http://www.neoconix.com>
sales@neoconix.com

PCBeam™ is a trademark of Neoconix Incorporated.

REVISION HISTORY

Rev A	02/05/2021	Production Release
Rev B	01/20/2017	Updated environmental specs.
Rev C	08/09/2017	Updated cross reference info
Rev D	10/26/2018	Updated packaging info to 3kpcs per carton (ECN 1218)
Rev E	3/5 / 2021	Change flange from dual tip to single tip, increase flange height spec.

DOCUMENT NUMBER: AS-000024	REV. E 3/5/2021	100-pin Interposer	AUTHOR: WT	Page 6 of 6
--------------------------------------	---------------------------	--------------------	----------------------	-----------------------